

<b>Notice of References Cited</b>	Application/Control No. 09/254,939	Applicant(s)/Patent Under Reexamination MIURA ET AL.	
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**U.S. PATENT DOCUMENTS**

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
	A	US-			
	B	US-			
	C	US-			
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**FOREIGN PATENT DOCUMENTS**

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**NON-PATENT DOCUMENTS**

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)
	U	M.Y. Lee et al., An Optimized Densification of the Filled oxide for Quarter Micron Shallow Trench (STI). IEEE, June 1996. (Abstract)
	V	
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\*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)  
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